

Title (en)

METHOD FOR OBTAINING A METAL MICROSTRUCTURE AND MICROSTRUCTURE OBTAINED ACCORDING TO SAID METHOD

Title (de)

VERFAHREN ZUR GEWINNUNG EINER METALLMIKROSTRUKTUR UND ANHAND DIESES VERFAHRENS GEWONNENE MIKROSTRUKTUR

Title (fr)

PROCÉDÉ DE FABRICATION D'UNE MICROSTRUCTURE MÉTALLIQUE ET MICROSTRUCTURE OBTENUE SELON CE PROCÉDÉ

Publication

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Application

**EP 08867895 A 20081219**

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Abstract (en)

[origin: WO2009083488A1] The invention relates to a method for making a metal microstructure, characterised in that it comprises the steps of forming, by a LIGA-UV method, a mould made of a photosensitive resin, and galvanically and uniformly depositing a layer of a first metal then a layer of a second metal in order to form a block that substantially reaches the upper surface of the photosensitive resin.

IPC 8 full level

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